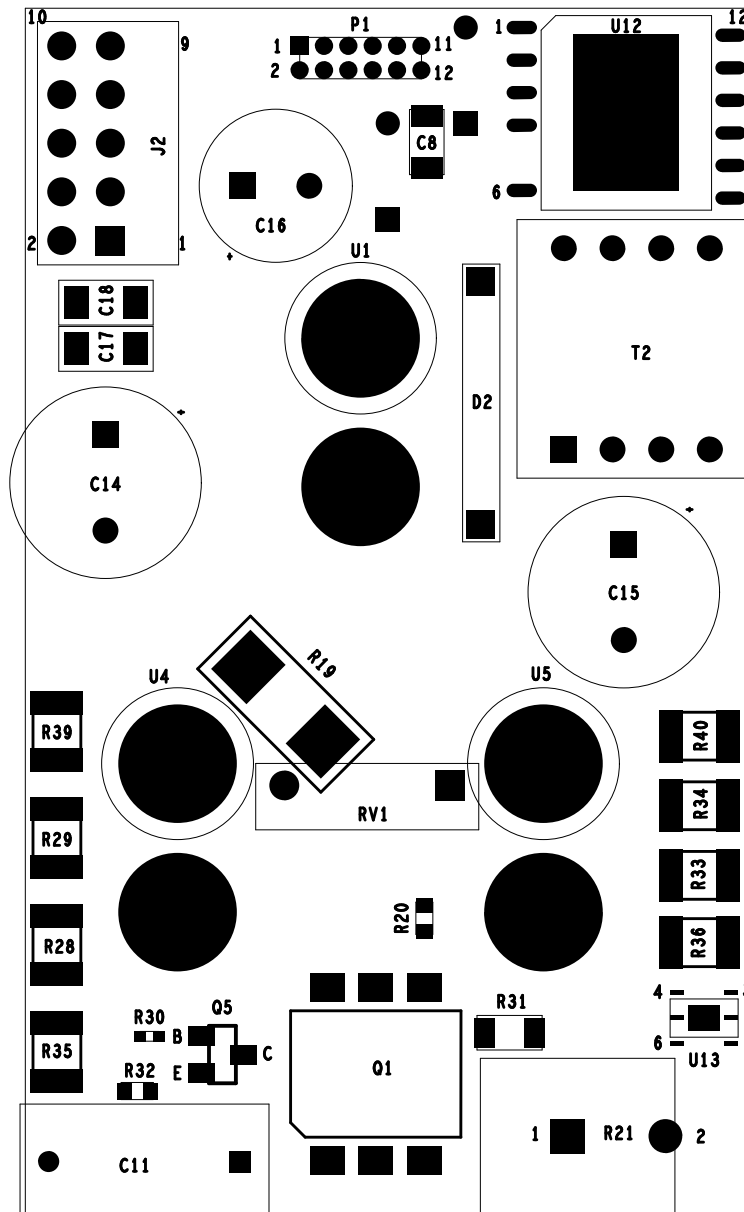


POWER BOARD

DATE: 03/08/2015

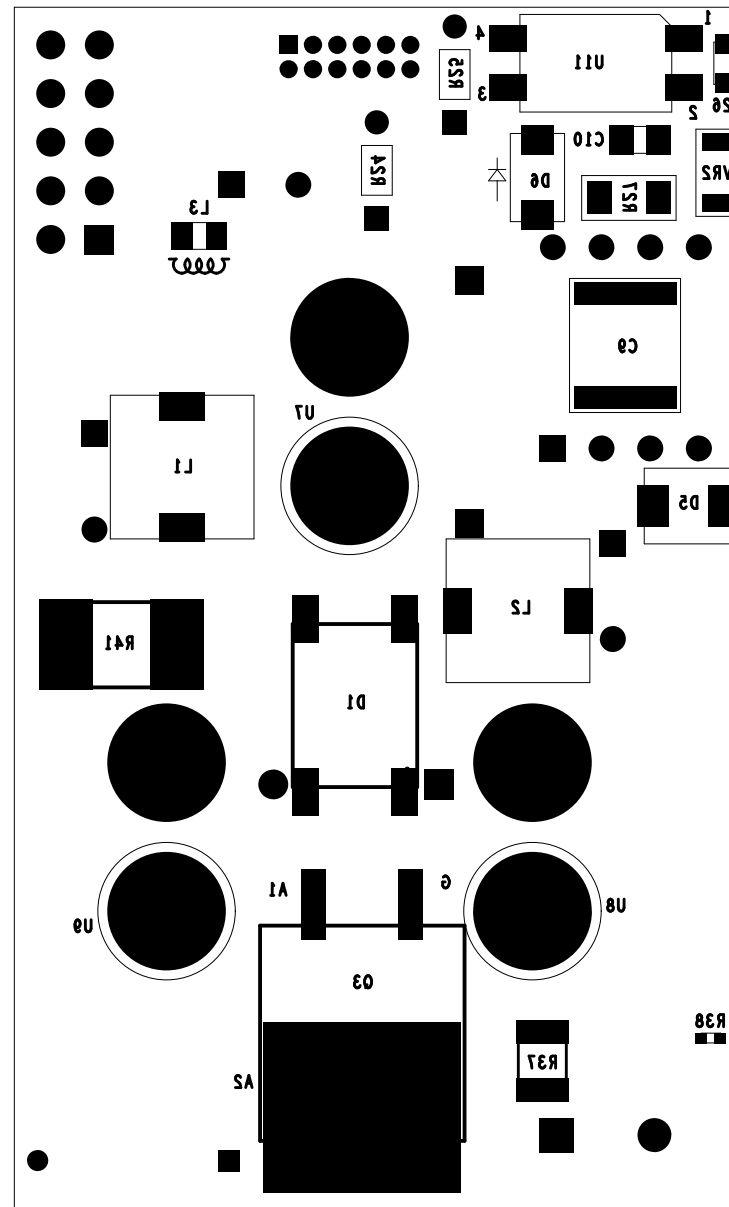
ASSEMBLY TOP



POWER BOARD

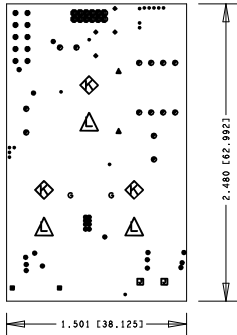
DATE: 03/08/2015

ASSEMBLY BOTTOM



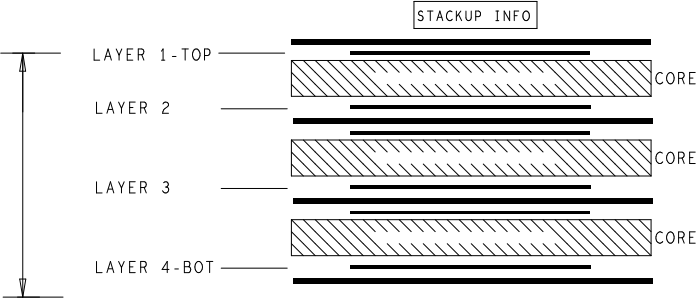
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+3.0/-3.0	PLATED	23
•	16.0	+3.0/-3.0	PLATED	16
▪	23.62	+3.0/-3.0	PLATED	2
●	25.59	+3.0/-3.0	PLATED	12
•	29.84	+3.0/-3.0	PLATED	4
•	33.62	+0.0/-0.0	PLATED	14
▲	37.95	+3.0/-3.0	PLATED	2
•	40.0	+3.0/-3.0	PLATED	10
•	41.5	+3.0/-3.0	PLATED	2
▪	50.0	+3.0/-3.0	PLATED	2
◊	125.0	+3.0/-3.0	PLATED	3
△	165.35	+3.0/-3.0	PLATED	3

POWER BOARD
DATE: 03/08/2015
FAB_DRAWING



62.992 MILS
(1.6 MM)

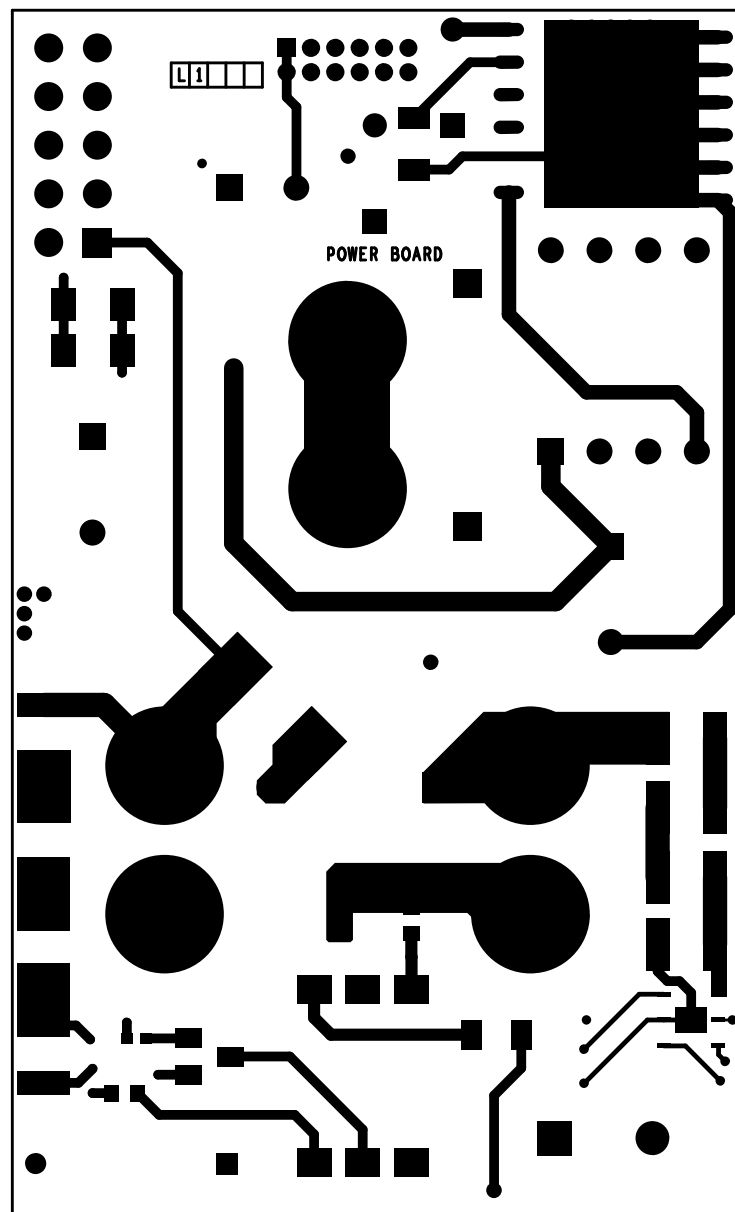
- NOTES:
1. ALL ARTWORK PATTERNS ARE VIEWED FROM THE TOP.
 2. PLATING FINISH METHOD SHALL BE HASL
 3. SOLDER MASK OVER BARE COPPER (SMOBC) SHALL BE ON BOTH SIDES.
 4. MASK COLOUR IS GREEN AND TYPE IS LPI
 5. BOARD THICKNESS IS 1.6 MM
 6. COPPER THICKNESS FOR OUTER LAYERS IS 35 MICRONS
 7. PCB MATERIAL IS FR4
 8. STACKUP SPECIFICATIONS IS AS FOLLOWS
 9. SIGNAL TRACE WIDTH 6 MILS POWER TRACEWIDTH 30 MILS (MIN 20 MILS)
 10. IF VIA IN PAD (VIP) SHOULD BE FILLED AND PLATED WITH PLANNER



POWER BOARD

DATE: 03/08/2015

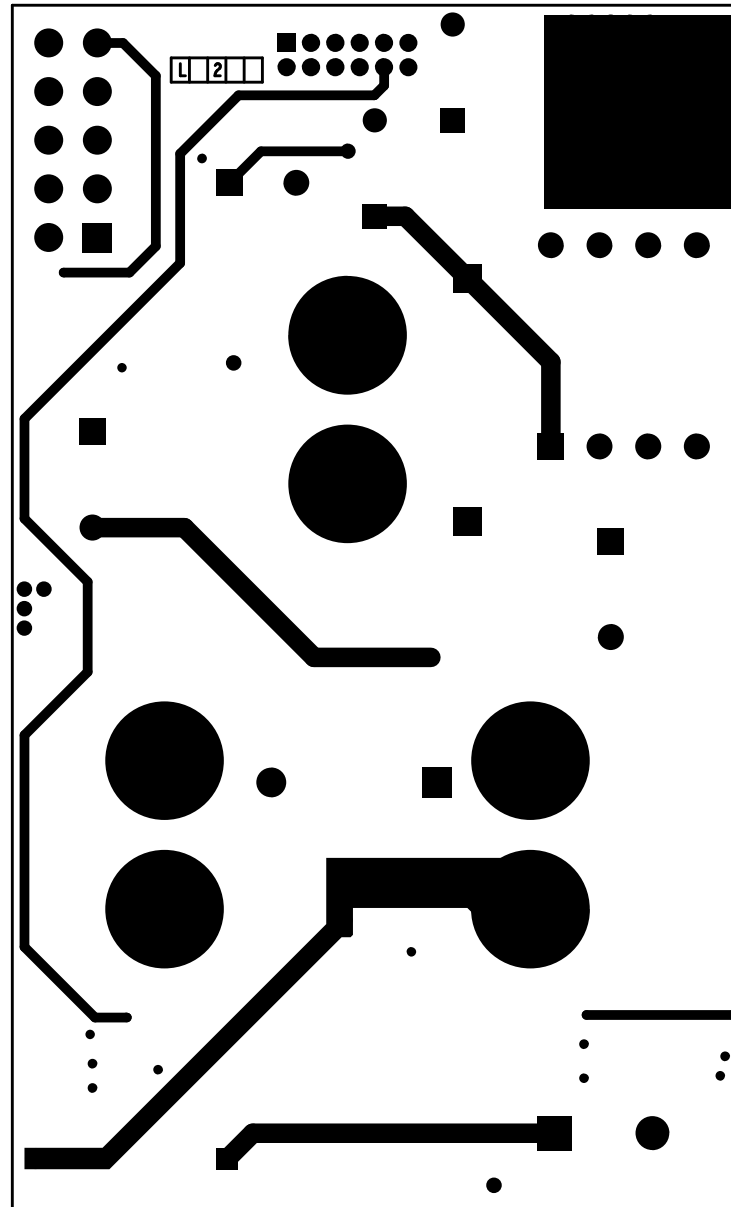
L01_TOP



POWER BOARD

DATE: 03/08/2015

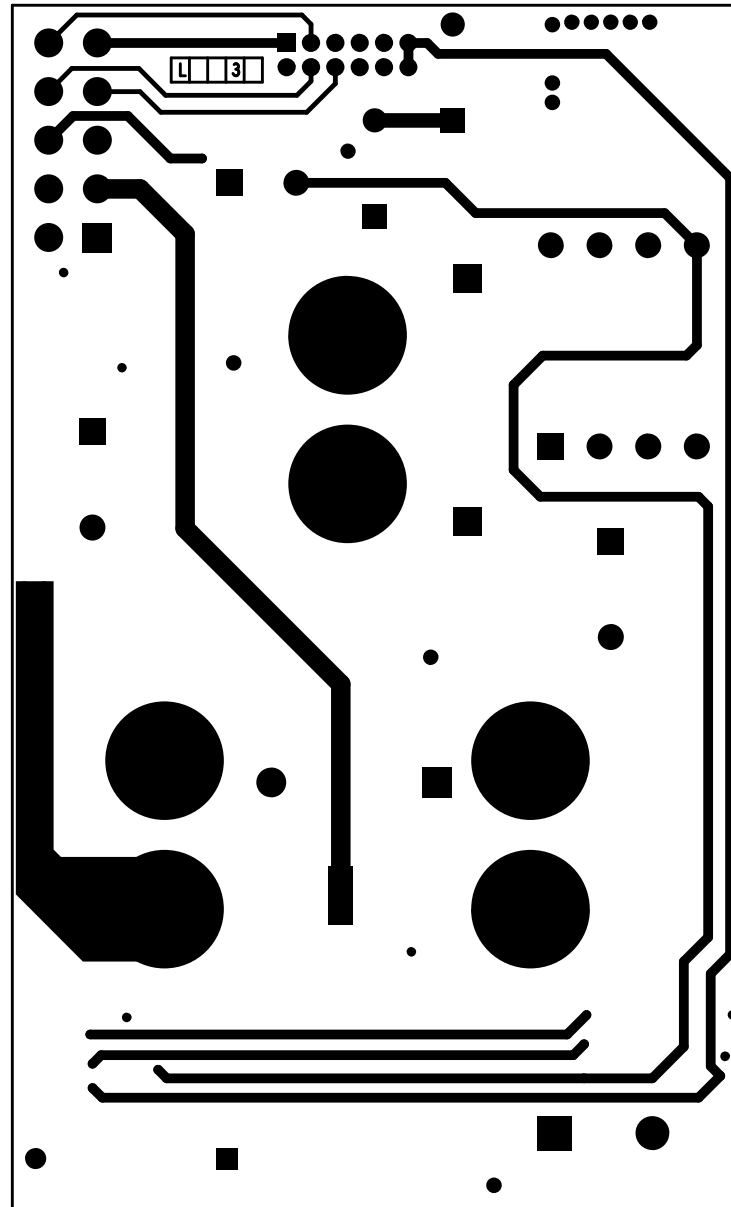
L02_SIG1



POWER BOARD

DATE: 03/08/2015

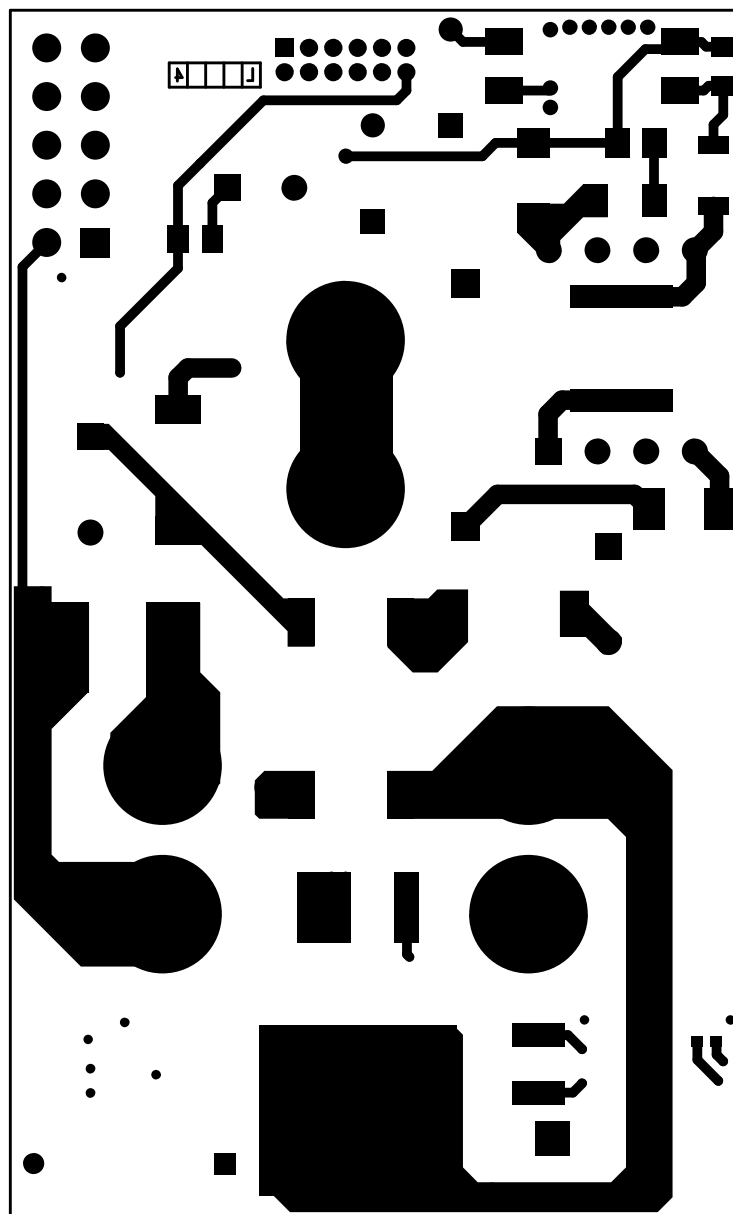
L03_SIG2



POWER BOARD

DATE: 03/08/2015

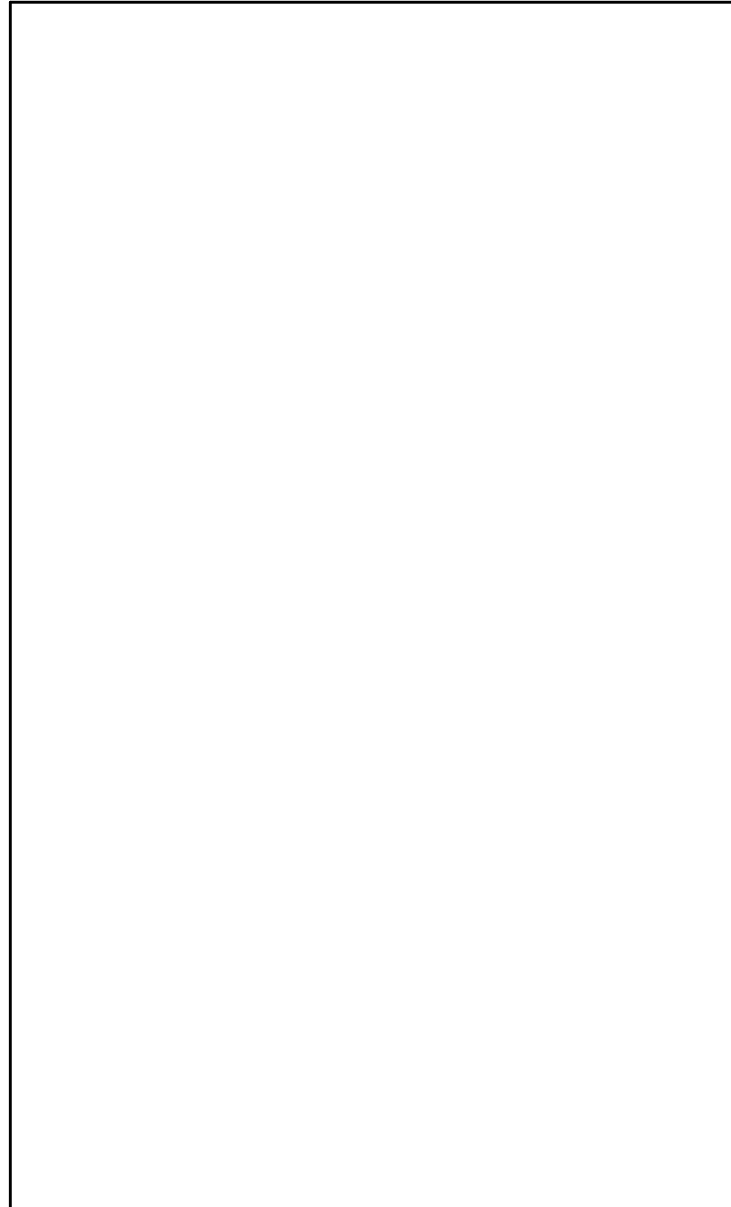
L04_BOTTOM



POWER BOARD

DATE: 03/08/2015

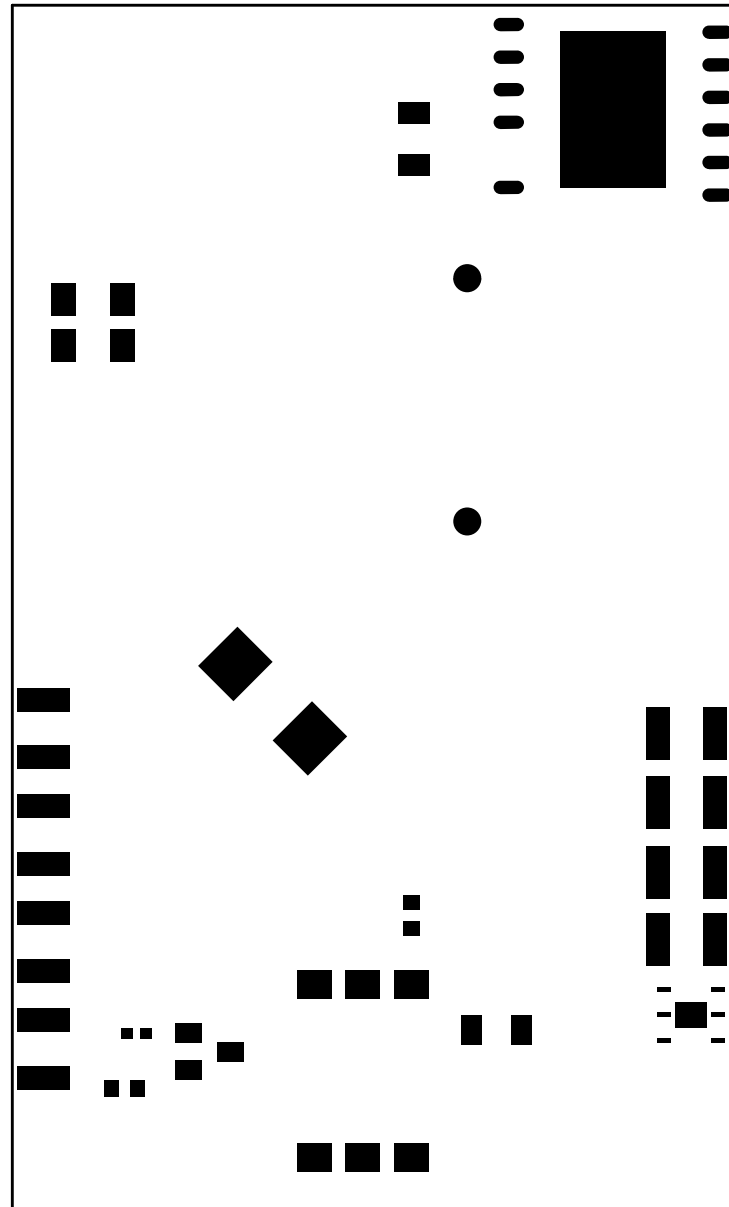
OUTLINE



POWER BOARD

DATE: 03/08/2015

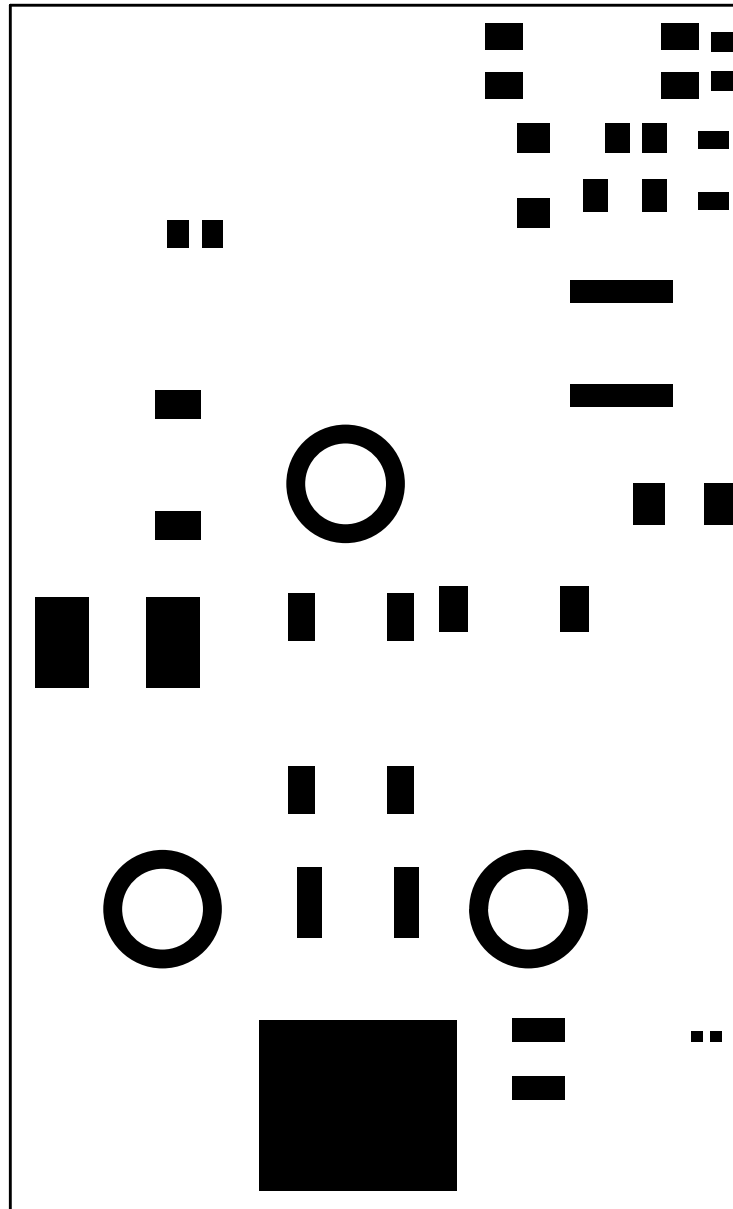
PASTEMASK TOP



POWER BOARD

DATE: 03/08/2015

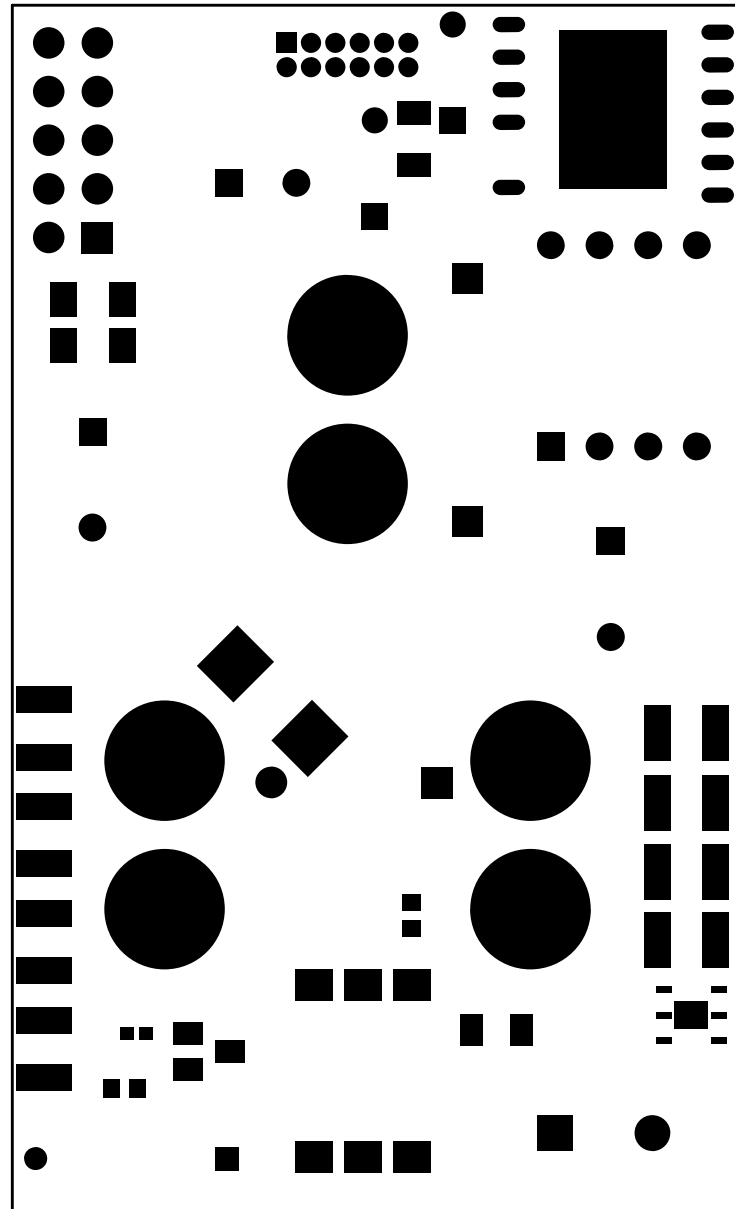
PASTEMASK BOTTOM



POWER BOARD

DATE: 03/08/2015

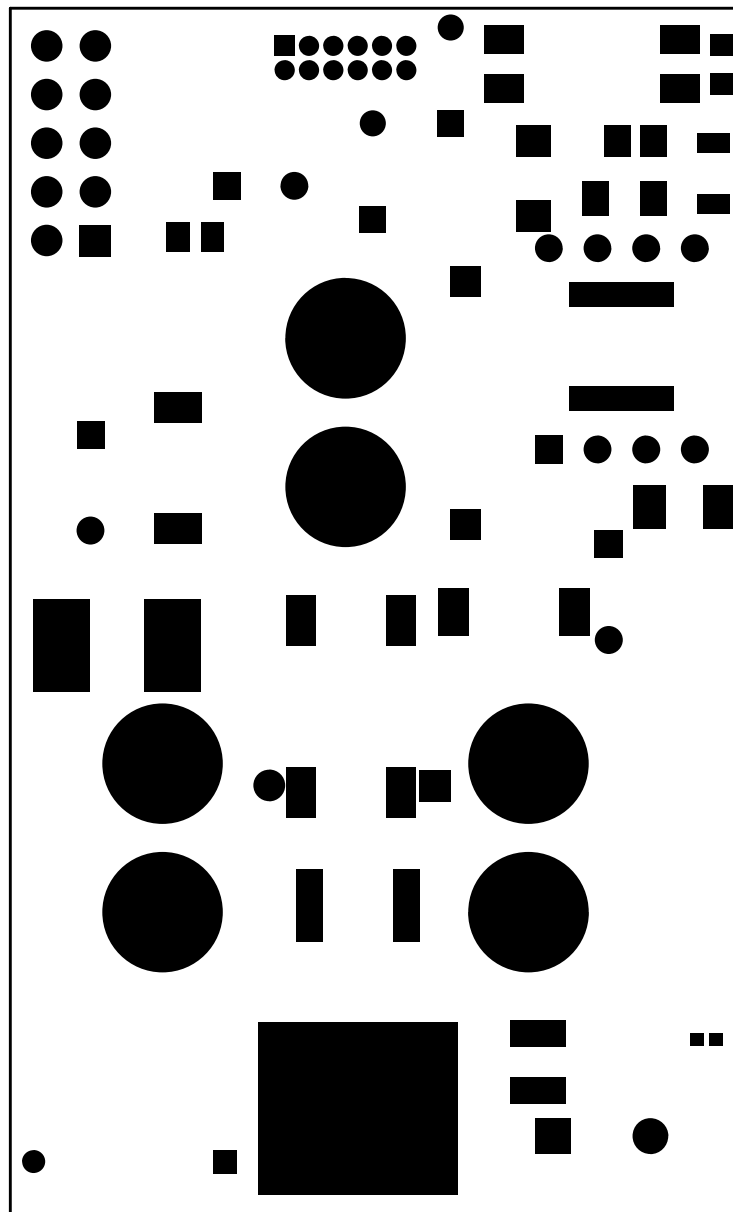
SOLDERMASK TOP



POWER BOARD

DATE: 03/08/2015

SOLDERMASK BOTTOM



POWER BOARD

DATE: 03/08/2015

SILKSCREEN TOP

